

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

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|--|--|----------------|---------------|-------------|----------------|--|---------------|-------|
| Title of Invention | [HEAT SINK FOR CHIP PACKAGE AND BONDING METHOD THEREOF] | | | | | | | |
| Application Number : | | | | | | | | |
| Date : | | | | | | | | |
| First Named Applicant: | Mr. Sung-Fei Wang | | | | | | | |
| Confirmation Number: | | | | | | | | |
| Attorney Docket Number: | 10233-US-PA | | | | | | | |
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| <table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Dr. Belinda Lee Registered Number: 46,863</td><td>/Belinda Lee/</td><td>Agent</td></tr></table> | | | Submitted By: | Elec. Sign. | Sign. Capacity | Dr. Belinda Lee Registered Number: 46,863 | /Belinda Lee/ | Agent |
| Submitted By: | Elec. Sign. | Sign. Capacity | | | | | | |
| Dr. Belinda Lee Registered Number: 46,863 | /Belinda Lee/ | Agent | | | | | | |

| Documents being submitted: | Files |
|---|---|
| us-request | 10233-usrequ.xml us-request.dtd us-request.xsl |
| us-assignment | 10233-usassn.xml us-assignment.xsl us-assignment.dtd 10233assignment2.tif 10233assignment1.tif |
| us-fee-sheet | 10233-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd |
| application-body | 10233-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd 10233US0001.tif 10233US0002.tif 10233US0003.tif |
| us-declaration | 10233declaration1.tif |
| us-declaration | 10233declaration2.tif |
| Comments Please be kindly advised that the indicated fees of this EFS application is intended to be paid by credit card. However, in the event that the payment through credit card is unsuccessful, the Commissioner is authorized to charge the required fees in connection with this application to: Deposit Account No. 50-2620 (Order No. 10233-US-PA), Deposit Account Name: Jianq Chyun Intellectual Property Office, Authorized User Name: Belinda Lee, E-mail: belinda@jcipgroup.com.tw; usa@jcipgroup.com.tw | |